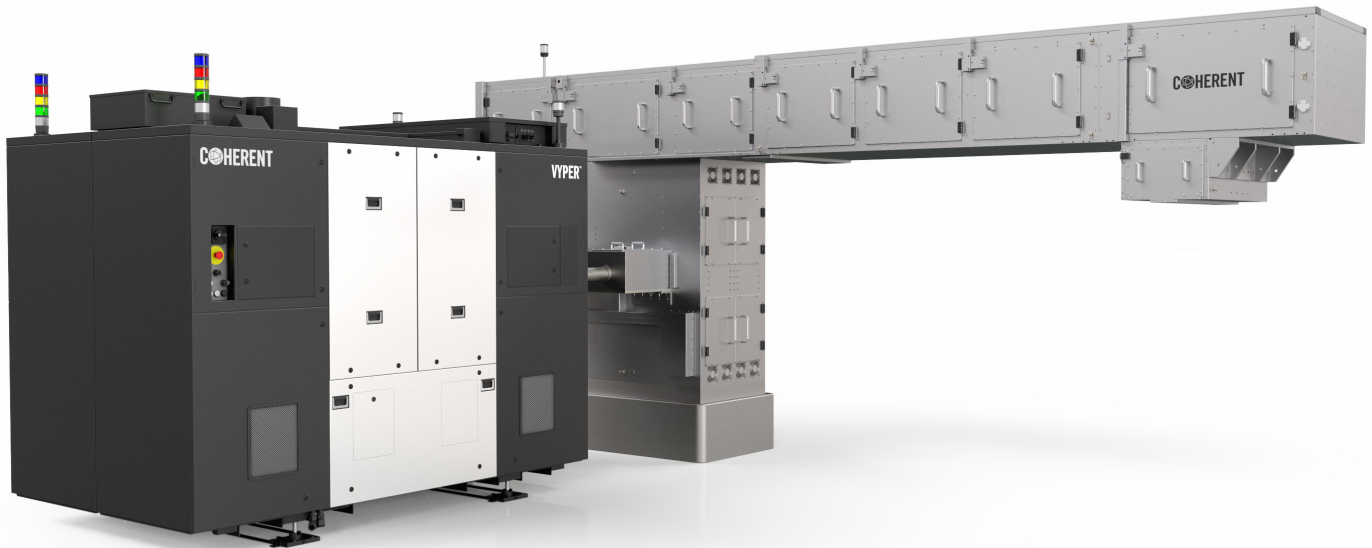


# UVblade

## Laser Lift-Off Processing

UVblade gently detaches delicate polymer-based displays of all types from their rigid glass carriers. Laser Lift-Off separation is the enabling technology in manufacturing flexible displays. UVblade is available at variable line beam lengths supporting fast and effective separation of substrates and wafers.



### FEATURES

- Cost effective solutions for Laser Lift-Off (LLO) separation
- Pulse on Demand (POD)
- Unmatched beam utilization
- Scalability in line lengths and energy density
- Flexible system footprint

### APPLICATIONS

- Laser Lift-Off Separation of Wafers and Displays
- Unique Lift-Off Solution for Transparent and Colorless Polyimide (CPI)

Specifications	UVblade 380	UVblade 750-N	UVblade 750HP	UVblade 1250
Wavelength (nm)	308	308	308	308
Laser Pulse Energy (mJ)	1000	1000	2000	2000
Repetition Rate (Hz)	600	600	600	600
Energy Density (mJ/cm <sup>2</sup> ) (at 96%)	450	260	430	270
Beam Length (mm)	380	750	750	1250
Beam Width (μm) (at 96%)	400	320	400	400
Homogeneity Long Axis (% 2σ)	1.8	1.8	1.8	1.8
Depth of Focus (μm)	±150	±150	±150	±120

### UVblade Performance

Example of UVblade 750 2D-beam profile, short and long axis cross sections in the substrate plane

